

Data sheet Product ICK BGA 10 x 10

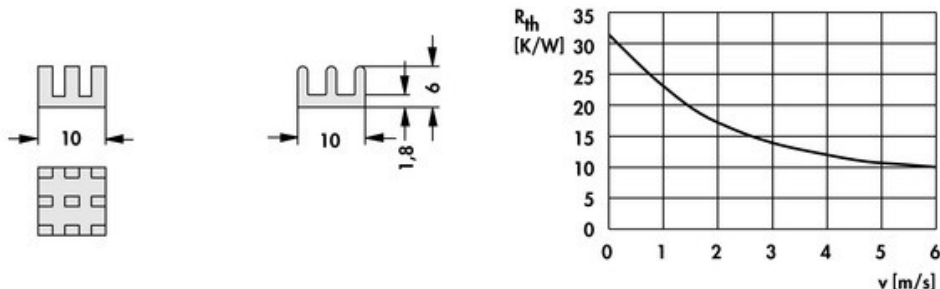


- Heatsinks and active heatsinks for processors>Heatsinks for BGAs
 10 x 10 x 6 mm, for IC design BGA and others
- particularly suited for **Ball Grid Arrays**
 - heatsink dimensions match the respective BGA-type
 - can be glued directly on the BGA component
 - double-sided adhesive thermal conductive foil **WLF ...**
 - **surface:** black anodised

Features

way of fixation:	• therm. conductive foil • therm. cond. adhesive
socket:	universal
suitable for processor type:	universal
width:	10 mm
height:	6 mm
plate thickness:	1.8 mm
length:	10 mm
thermal resistance:	32 - 10 K/W
dissipation loss:	1.8 W
surface:	black anodised

Technical Drawing



Fischer Elektronik GmbH & Co. KG
DEUTSCHLAND • GERMANY • ALLEMAGNE

Nottebohmstraße 28
58511 Lüdenscheid

Telefon +49 2351 435-0
Telefax +49 2351 45754

info@fischerelektronik.de
www.fischerelektronik.de